

/ Descriptions

Silicon PNP transistor in a TO-252 Plastic Package.

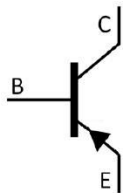
/ Features

Low Speed ,Load Formed for Surface Mount Application.

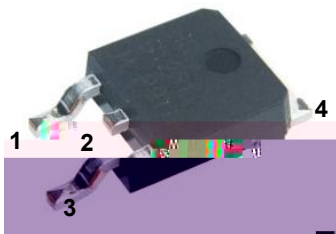
/ Applications

General Purpose Amplifier.

/ Equivalent Circuit



/ Pinning



PIN1 Base PIN 2,4 Collector PIN 3 Emitter

/ h_{FE} Classifications & Marking

See Marking Instructions.

/ Absolute Maximum Ratings(Ta=25)

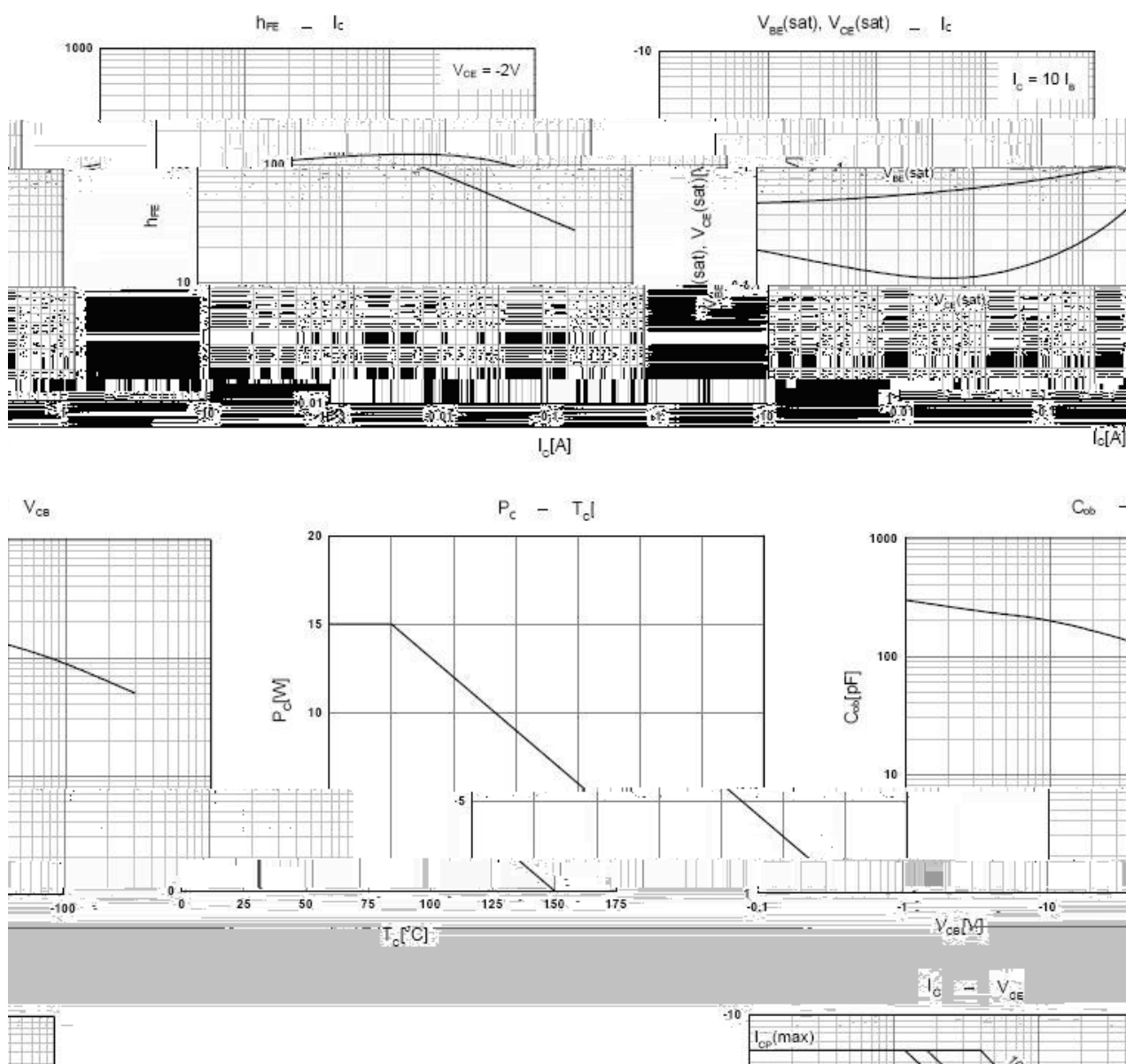
Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-100	V
Collector to Emitter Voltage	V_{CEO}	-100	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current - Continuous	I_C	-3.0	A
Collector Current – Continuous(Pulse)	I_{CP}	-5.0	A
Base Current - Continuous	I_B	-1.0	A
Collector Power Dissipation	$P_C(T_C=25)$	15	W
Collector Power Dissipation	P_C	1.56	W
Junction Temperature	T_J	150	
Storage Temperature Range	T_{stg}	-65 150	

/ Electrical Characteristics(Ta=25)

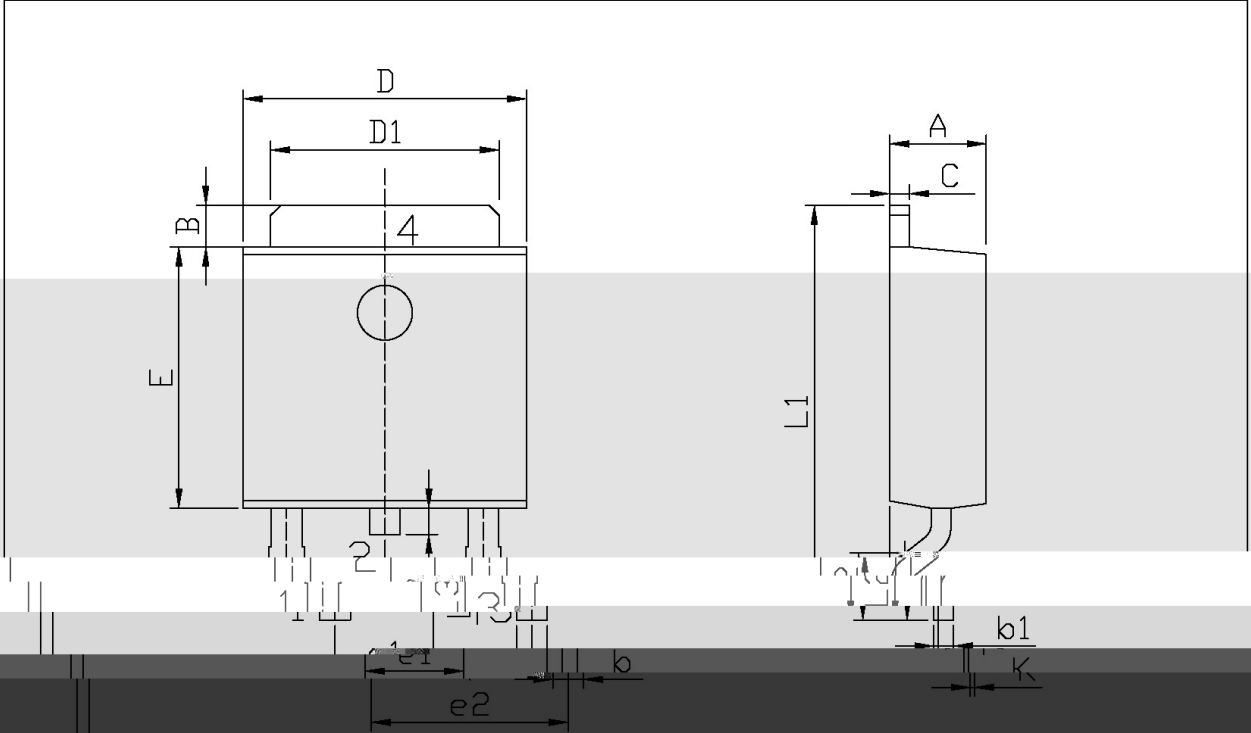
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Emitter Breakdown Voltage*	$*V_{CEO}$	$I_C=-30mA$ $I_B=0$	-100			V
Collector Cut-Off Current	I_{CEO}	$V_{CE}=-60V$ $I_B=0$			-50	μA
Collector Cut-Off Current	I_{CES}	$V_{CE}=-100V$ $V_{BE}=0$			-20	μA
Emitter Cut-Off Current	I_{EBO}	$V_{BE}=-5.0V$ $I_C=0$			-1.0	mA
DC Current Gain*	$*h_{FE}$	$V_{CE}=-4.0V$ $I_C=-3.0A$	15		75	
Collector to Emitter Saturation Voltage*	$*V_{CE(sat)}$	$I_C=-3.0A$ $I_B=-375mA$			-1.2	V
Base to Emitter On Voltage*	$*V_{BE(on)}$	$V_{CE}=-4.0A$ $I_C=-3.0A$			-1.8	V
Current- Gain Bandwidth Product	f_T	$V_{CE}=-10V$ $I_C=-100mA$	3			MHz

*:pw() $\leq 300\mu s$,duty cycle() $\leq 2\%$.

/ **Electrical Characteristic Curve**



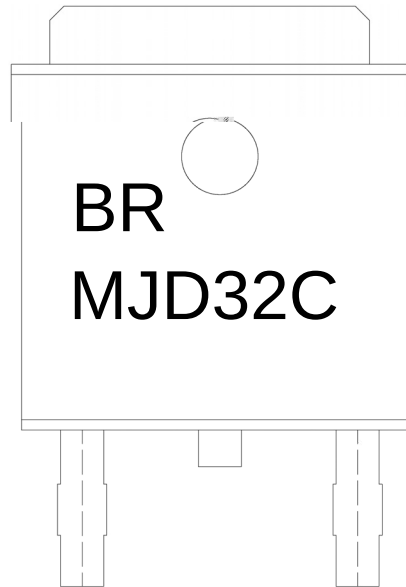
/ Package Dimensions



单位: mm

Dimensions In Millimeters			Dimensions In Millimeters		
Symbol	Min	Max	Symbol	Min	Max
A	2.20	2.40	E	5.95	6.25

/ **Marking Instructions**



BR

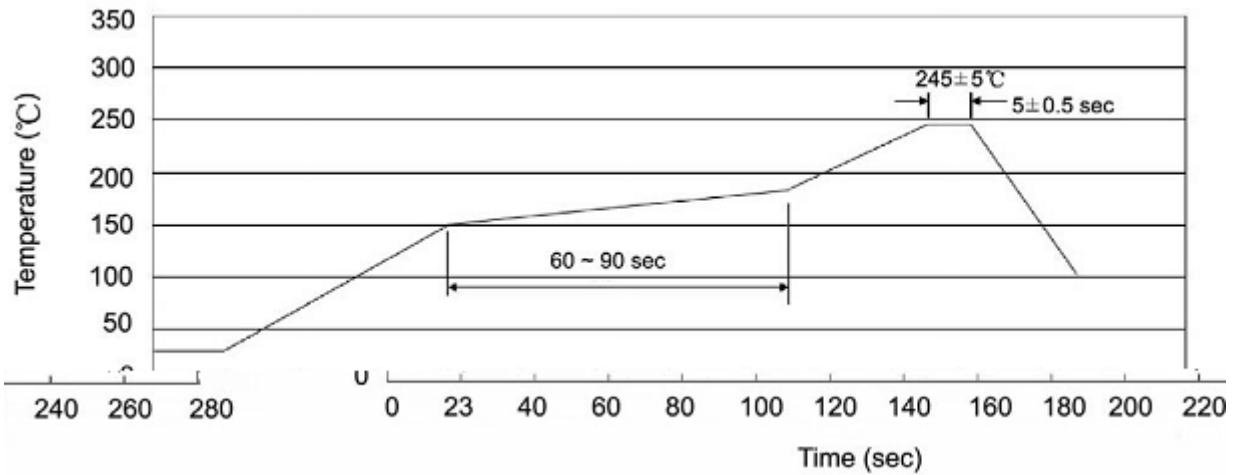
Note:

BR: Company Code

MJD32C: Product Type.

***: Lot No. Code, code change with Lot No.

() / **Temperature Profile for IR Reflow Soldering(Pb-Free)**



Note:

- | | | | | | |
|---|-----|-----|----|----------|---|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 245 | 5 | 5 | 0.5sec; | 2.Peak Temp.:245 5 , Duration:5 0.5sec. |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. |

/ **Resistance to Soldering Heat Test Conditions**

260 5 10 1 sec. Temp.:260±5 Time:10±1 sec

/ **Packaging SPEC.**

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱

/ TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 套管	套管 盒	只 盒	盒 箱	只 箱	套管	盒	箱

/ **Notices**